



EMPLAGE

MATIERE FR4 (voir empilage)
CUIRE 35 Microns 2 faces
TECHNO DOUBLE FACE
VERNIS SELECTIF -VERT 2 FACES
SERIGRAPHIE BLANCHE FACE TOP
FINITION NiAu

IMPEDANCE
PISTES 1.064mm 50 ohms
PISTES .200mm 100 ohms

Layer	Name	Material	Thickness	Constant	Board Layer Stack	Board Layer Stack	Board Layer Stack
1	TopOverlay						
2	TopSolder	Solder Resist	0,020mm	4			
3	TopLayer	Copper	0,035mm				
4	Dielectricl	FR-4	1,465mm	4,74			
5	BottomLayer	Copper	0,035mm				
6	BottomSolder	Solder Resist	0,020mm	4			
7	BottomOverlay						

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
⊙	1	1,219mm (<48,00mil)	PTH	Round	TopLayer - BottomLayer	Pad
▽	1	1,651mm (<65,00mil)	PTH	Round	TopLayer - BottomLayer	Pad
⊗	3	1,170mm (<46,06mil)	PTH	Round	TopLayer - BottomLayer	Pad
○	4	0,406mm (<16,00mil)	PTH	Round	TopLayer - BottomLayer	Pad
■	5	0,813mm (<32,00mil)	PTH	Round	TopLayer - BottomLayer	Pad
✱	10	0,711mm (<28,00mil)	PTH	Round	TopLayer - BottomLayer	Via
□	13	3,300mm (<129,92mil)	PTH	Round	TopLayer - BottomLayer	Pad
▽	15	1,168mm (<46,00mil)	PTH	Round	TopLayer - BottomLayer	Pad
✱	16	1,702mm (<67,00mil)	PTH	Round	TopLayer - BottomLayer	Pad
⊙	67	0,965mm (<38,00mil)	PTH	Round	TopLayer - BottomLayer	Pad
⊗	78	0,508mm (<20,00mil)	PTH	Round	TopLayer - BottomLayer	Via
✱	4234	0,300mm (<11,81mil)	PTH	Round	TopLayer - BottomLayer	Via
	4447 Total					

Radio Oceanography Laboratory

Indice

Modification

Date

Dessine par

Edition : CARTE CRX-8-21

Dessinateur : RONVEL

Date : 30-03-21

PLAN DE PERCAGE

Folio : 1 / 1

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